

GW1NS & GW1NSR & GW1NSE & GW1NSER Series of FPGA Products Schematic Manual

Introduction

You should follow some rules for circuit board design when using GW1NS & GW1NSR & GW1NSE & GW1NSER series of FPGA products. This manual describes the characteristics of GW1NS & GW1NSR & GW1NSE & GW1NSER series of FPGA products. The main contents of this manual are as follows:

- Power Supply
- JTAG
- MSPI
- Clock Pin
- Difference Pin
- READY, RECONFIG_N, DONE
- MODE
- JTAGSEL_N
- FASTRD_N
- Configure Dual-purpose Pin
- External Crystal Oscillator Circuit Reference
- Bank Voltage
- Configuration Modes Supported by Each Device
- MIPI
- ADC
- USB
- Pinout

Power Supply

Overview

GW1NS & GW1NSR & GW1NSE & GW1NSER series of FPGA products support LX, UX and LV versions. The voltage includes core voltage (V_{CC}), auxiliary voltage (V_{CCX}) and bank voltage (V_{CC0}).

There is no linear voltage regulator in devices of LX version, and V_{CCX} needs to be set to 1.8V. The I/O Bank voltage V_{CC0} can be set to 1.2 V, 1.5 V, or 1.8 V as required.

There is linear voltage regulator in devices of UX, and V_{CCX} can be set to 2.5 V or 3.3V. The I/O Bank voltage V_{CC0} can be set to 1.2 V, 1.5 V, 1.8 V, 2.5 V, or 3.3 V as required. It should be noted that V_{CCX} needs to be greater than or equal to V_{CC0} .

There is no linear voltage regulator in devices of LV version, and V_{CCX} can be set to 1.8V, 2.5V or 3.3V. The I/O Bank voltage V_{CC0} can be set to 1.2 V, 1.5 V, 1.8 V, 2.5 V, or 3.3 V as required.

Note!

LX and LX versions have the same functions, and the pins are compatible.

V_{CC} of these three versions is 1.2V. V_{CCX} is the auxiliary power, which is used to supply some circuits in the chip, supporting 1.8V, 2.5V and 3.3V. After the chip powers on, V_{CCX} can be turned off. V_{CC0} Bank can be set to 1.2V, 1.5V, 1.8V, 2.5V, or 3.3V as required.

Power Index

The device can only operate when the power voltage is in the recommended range. Table 1 lists the recommended range.

Table 1 Recommended Range

Name	Description	Min.	Max.
V_{CC}	Core voltage	1.14V	1.26V
V_{CC0x}	I/O Bank voltage for LX version	1.14V	1.89V
	I/O Bank voltage for UX version V_{CCX} needs to be greater than or equal to V_{CC0x} for UX version.	1.14V	3.465V
	I/O Bank voltage for LV version	1.14V	3.465V
V_{CCX}	Auxiliary voltage for LX version	1.71V	1.89V
	Auxiliary voltage for UX version V_{CCX} needs to be greater than or equal to V_{CC0x} for UX version.	2.375V	3.465V
	Auxiliary voltage for LV version	1.71V	3.465V

Power Consumption

For specific density, packages, and resource utilization, you can use GPA tool to evaluate and analyze the power consumption.

Power Rising Slope

The reference for power-on time: 0.01mV/ μ s ~ 10mV/ μ s.

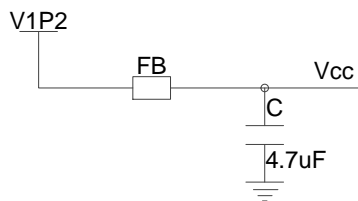
Power Filter

Each FPGA power input pin is connected to the ground with a 0.1uF ceramic capacitor.

Noise processing should be noted at the input end of the V_{CC} , and the

specific is as follows:

Figure 1 Noise Processing



FB is a magnetic bead, and the reference model is MH2029-221Y. The ceramic capacitance is 4.7uF, and It offers an accuracy of more than $\pm 20\%$.

JTAG

Overview

JTAG interface is used for downloading the bitstream to SRAM, on-chip flash or off-chip flash of FPGA.

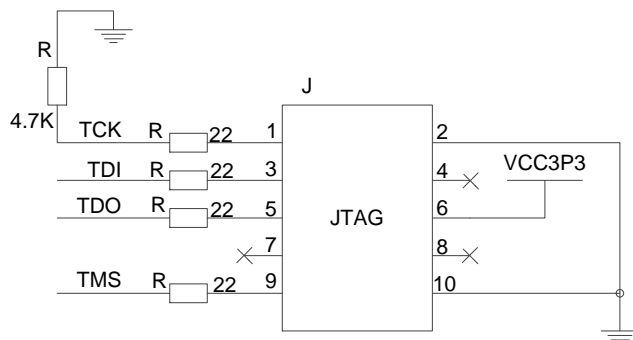
Signal Description

Table 2 Signal Description

Name	I/O	Description
TCK	I	JTAG serial clock input
TMS	I, internal weak pull-up	JTAG serial mode input
TDI	I, internal weak pull-up	JTAG serial data input
TDO	O	JTAG serial data output

JTAG Circuit Reference

Figure 2 JTAG Circuit Reference



Note!

- The resistance accuracy is not less than $\pm 5\%$;
- The power of JTAG 6th pin can be set to VCC1P2, VCC1P5, VCC1P8, VCC2P5 as required.

MSPI

Overview

FPGA as a master device, MSPI reads the data automatically from the off-chip flash then transmits it to the FPGA SRAM.

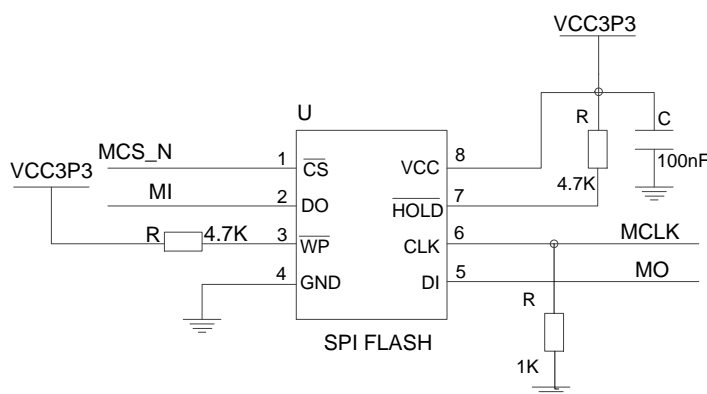
Signal Description

Table 3 Signal Description

Name	I/O	Description
MCLK	O	Clock output in MSPI mode
MCS_N	O	MCS_N in MSPI mode, low-active
MI	I	Data input in MSPI mode
MO	O	Data output in MSPI mode

MSPI Circuit Reference

Figure 3 MSPI Circuit Reference



Note!

- MCLK signal requires 1K pull-down resistor.
- The resistance accuracy is not less than $\pm 5\%$.

Clock Pins

Overview

The clock pins include GCLK global clock pins and PLL clock pins.

- GCLK: GCLK in FPGA products distributes in L and R quadrants. Each quadrant provides eight GCLK nets. The clock source of each GCLK can be dedicated pin or CRU, and the dedicated pin can provide better performance.
- PLL: Frequency (multiplication and division), phase, and duty cycle can be adjusted by configuring the parameters.

Signal Description

Table 4 Signal Description

Name	I/O	Description
GCLKT_[x]	I/O	Pins in global clock input, T(True), [x]: global clock No.
GCLKC_[x]	I/O	Pins for Global clock input, C(Comp), [x]: global clock No.
LPLL_T_fb/RPLL_T_fb	I	Left/Right PLL feedback input pins, T(True)
LPLL_C_fb/RPLL_C_fb	I	Left/Right PLL feedback input pins, C(Comp)
LPLL_T_in/RPLL_T_in	I	Left/Right PLL clock input pin, T(True)
LPLL_C_in/RPLL_C_in	I	Left/Right PLL clock input pin, C(Comp)

Clock Input Selection

If the external clock as PLL clock, it is recommended to input from PLL_T.

GCLK is the global clock and is connected to all resources in the device. It is recommended to input from GCLK_T.

Differential Pins

Overview

Differential transmission is a kind of signal transmission, which is different from the traditional signal line and ground line. Differential transmission signals are transmitted on these two lines. These two signals are with same amplitude, phase and opposite polarity.

Differential Type

Figure 5 Differential Type

I/O output standard	Single/Differ	Bank V _{CCO} (V)	Output Driver Strength (mA)
LVPECL33E	Differential	3.3	16
MVLDS25E	Differential	2.5	16
BLVDS25E	Differential	2.5	16
RSDS25E	Differential	2.5	8
LVDS25E	Differential	2.5	8
LVDS25	Differential	2.5/3.3	3.5/2.5/2/6
RSDS	Differential	2.5/3.3	2
MINILVDS	Differential	2.5/3.3	2
PPLVDS	Differential	2.5/3.3	3.5
SSTL15D	Differential	1.5	8

I/O output standard	Single/Differ	Bank V _{CCO} (V)	Output Driver Strength (mA)
SSTL25D_I	Differential	2.5	8
SSTL25D_II	Differential	2.5	8
SSTL33D_I	Differential	3.3	8
SSTL33D_II	Differential	3.3	8
SSTL18D_I	Differential	1.8	8
SSTL18D_II	Differential	1.8	8
HSTL18D_I	Differential	1.8	8
HSTL18D_II	Differential	1.8	8
HSTL15D_I	Differential	1.5	8

- Note!
- See pinout manuals for specific differential pin positions.

READY, RECONFIG_N, DONE

Overview

RECONFIG_N, equivalent to the reset function of FPGA programming configuration, FPGA cannot perform any configuration operation when RECONFIG_N is pulled down.

As a configuration pin, a low level with a pulse width of not less than 25ns is required for GowinCONFIG configuration mode to enable the device to reload the bitstream. You can control the pin by writing logic to trigger the device to reconfigure as required.

You can configure FPGA only when the READY signal is high. The device should be restored by power on or triggering RECONFIG_N when the READY signal is low.

As an output configuration pin, it can indicate whether the FPGA can be configured currently. If the device is ready, READY signal is high. If the device fails to configure, the READY signal changes to low. As an input configuration pin, you can delay the configuration by its own logic or pulling down the READY signal.

DONE signal indicates that the FPGA is configured successfully. The signal is high after successful configuration.

As an output configuration pin, it can indicate whether FPGA configuration is successful. If configured successfully, DONE is high, and the device enters into an operating state. If the device failed to configure, the DONE signal remains low. As the input, you can delay the entry into user mode by manually pulling down the DONE signal via the logic.

When RECONFIG_N or READY signals are low, DONE signal is also low. When configuring SRAM using JTAG circuit, it does not need to take DONE signal into account.

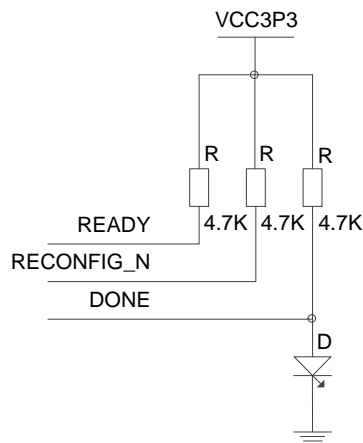
Signal Description

Table 6 Signal Description

Name	I/O	Description
RECONFIG_N	I, internal weak pull-up	Low level pulse: start new GowinCONFIG configuration
READY	I/O	High-level pulse: The device can be programmed and configured;
		Low-level pulse: The device cannot be programmed and configured,
DONE	I/O	High-level pulse: Successfully programmed and configured;
		Low-level pulse: Programming and configuration uncompleted or failed.

READY, RECONFIG_N, DONE Reference Circuit

Figure 4 READY, RECONFIG_N, DONE Reference Circuit



Note!

- The pull-up power supply is the bank voltage value VCC0 of the corresponding pin;
- The resistance accuracy is not less than $\pm 5\%$;

MODE

Overview

MODE includes MODE0, MODE1, MODE2, and GowinCONFIG. When FPGA powers on or a low pulse triggers RECONFIG_N, the device enters the corresponding GowinCONFIG state according to the MODE value. As the number of pins for each package is different, some MODE pins are not all packaged, and the unpacked MODE pins are grounded inside. Please refer to the corresponding pinout manual for further details.

Signal Description

Table 7 Signal Description

Name	I/O	Description
MODE2	I, internal weak pull-up	GowinCONFIG mode selection pin.
MODE1	I, internal weak pull-up	GowinCONFIG modes selection pin.
MODE0	I, internal weak pull-up	GowinCONFIG mode selection pin.

Mode Selection

Table 8 Mode Selection

Configuration Mode		MODE[2:0]	Description
JTAG		XXX	External Host configure FPGA products of LittleBee [®] Family via JTAG interface.
GowinCONFIG	AUTO BOOT	000	FPGA reads data from embedded Flash for configuration
	SSPI	001	External Host configure FPGA products of LittleBee [®] Family via SPI interface.
	MSPI	010	FPGA as Master, FPGA reads data from external Flash (or other devices) via the SPI interface for configuration.
	DUAL BOOT	110	FPGA reads data from external Flash first and if the external Flash fails, it reads from the internal Flash.
	SERIAL	101	External Host configure FPGA products of LittleBee [®] Family via DIN interface.
	CPU	111	External Host configure FPGA products of LittleBee [®] Family via DBUS interface.

JTAGSEL_N

Overview

JTAGSEL_N is JTAG mode selection signal. If the JTAG pin is set to GPIO in Gowin software, the JTAG pin changes to GPIO after the device is powered on to configure successfully. If JTAG configuration fails, you can recover by pulling down JTAGSEL_N. If you do not set JTAG multiplexing, the JTAG configuration function is always available.

Signal Description

Table 9 Signal Description

Pin Name	I/O	Description
JTAGSEL_N	I, internal weak pull-up	Change JTAG pin from GPIO to configuration pin, active-low

Note!

The JTAGSEL_N pin and four JTAG pins (TCK, TMS, TDI, and TDO) configured as GPIO are exclusive. JTAG pins can only be used as configuration pin if JTAGSEL_N is set to GPIO. JTAGSEL_N can only be used as a configuration pin if JTAG pins are set to GPIOs.

FASTRD_N

Overview

MSPI configuration mode reads the SPI Flash speed selection signal. When FASTRD_N is high, it is normal read mode. When FASTRD_N is low, it is high speed read mode. Different manufacturers have different high-speed read operation instructions, please refer to the corresponding Flash datasheet.

Signal Description

Table 10 Signal Description

Pin Name	I/O	Description
FASTRD_N	I/O	<ul style="list-style-type: none"> As a configuration pin, internal weak pull-up, READY signal rising edge samples MSPI configuration speed mode; As a GPIO, it can be used as input or output.

Note!

- High level: Normal Flash mode, clock frequency should not be higher than 30MHz;
- Low level: High speed Flash mode, clock frequency should be > 30MHz and < 80MHz

Configure Dual-purpose Pin

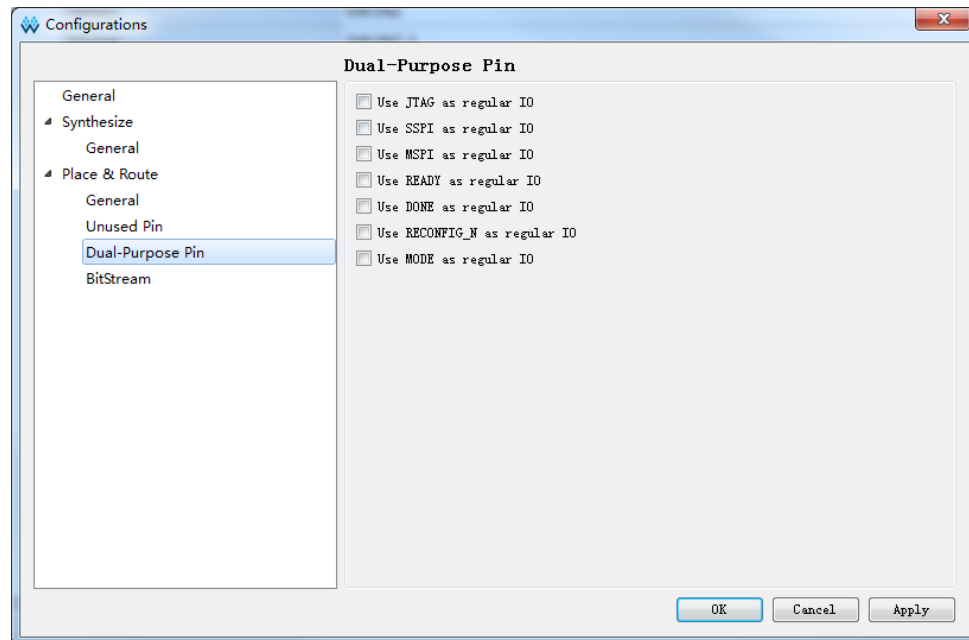
Overview

Dual-purpose pin configuration refers to performing configuration function at the moment of power-on. After downloading bitstream files, it is used as general I/O.

The steps are as follows:

1. Open the project in Gowin software;
2. Select "Project > Configuration > Dual Purpose Pin" from the menu, as shown in Figure 5;
3. Check the corresponding options.

Figure 5 Configure Dual-purpose Pin



Dual-purpose Pin

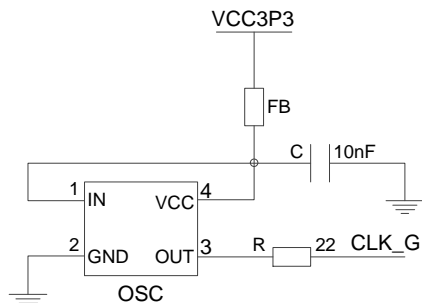
- SSPI: As a GPIO, SSPI can be used as input or output;
- MSPI: As a GPIO, MSPI can be used as input or output;
- RECONFIG_N GPIO can only be used as an output. Set the initial value of RECONFIG_N as high when multiplexing it.
- READY: As a GPIO, READY can be used as input or output. As an input GPIO, the initial value of READY should be 1. Otherwise, the FPGA will fail to configure;
- As a GPIO, DONE can be used as an input or output. If DONE is used as an input GPIO, the initial value of DONE should be 1. Otherwise, the FPGA will fail to enter the user mode after configuring;
- As a GPIO, JTAG can be used as an input or output;
- As a GPIO, JTAGSEL_N can be used as an input or output.
- As a GPIO, JTAG can be used as an input or output. You multiplex MODE pin, the correct value is needed to provided during configuration (power-on or low-level pulse triggers RECONFIG_N). Up to three pins can be multiplexed in MODE. Unpackaged pins are grounded internally. Please refer to pinout manual for details. For the MODE value corresponding to different configuration modes, please refer to the corresponding device manual.

Note!

If the number of I/O ports is sufficient, use non-multiplexed pins first.

FPGA External Crystal Oscillator Circuit Reference

Figure 6 FPGA External Crystal Oscillator Circuit



FB is a magnetic bead, and MH2029-221Y is the reference model. The resistance accuracy is not less than $\pm 5\%$, and capacitance accuracy is not less than $\pm 20\%$.

Bank Voltage

For the Bank power supply requirements of the devices, please refer to the Power section of the following documents.

- [UG825](#), GW1NS-2C Pinout
- [UG822](#), GW1NS-2 Pinout
- [UG824](#), GW1NS-4 & 4C Pinout
- [UG862](#), GW1NSR-2 & 2C Pinout
- [UG864](#), GW1NSR-4 Pinout
- [UG865](#), GW1NSR-4C Pinout
- [UG872](#), GW1NSE-2C Pinout
- [UG883](#), GW1NSER-4C Pinout

Configuration Modes Supported by Each Device

GW1NS-2

Table 11 GW1NS -2 Configuration Modes

Modes	JTAG	AUTO BOOT	DUAL BOOT	MSPI	SSPI	SERIAL	CPU
QN32	√	√	-	-	√	-	-
QN32U	√	√	-	-	-	-	-
CS36	√	√	-	-	-	-	-
CS36U	√	√	-	-	-	-	-
QN48	√	√	-	-	-	-	-
LQ144	√	√	√	-	√	√	√

GW1NS-2C

Table 12 GW1NS -2 C Configuration Modes

Modes	JTAG	AUTO BOOT	DUAL BOOT	MSPI	SSPI	SERIAL	CPU
QN32	√	√	-	-	√	-	-
QN32U	√	√	-	-	-	-	-
CS36	√	√	-	-	-	-	-
QN48	√	√	-	-	-	-	-
LQ144	√	√	√	-	√	√	√

GW1NS-4/4C

Table 13 GW1NS-4 / 4C Configuration Modes

Configuration Modes	JTAG	AUTO BOOT	MSPI
CS49	√	√	-
QN48	√	√	√
MG64	√	√	-

GW1NSR-2/2C

Table 14 GW1NSR-2 / 2 C Configuration Modes

Configuration Modes	JTAG	AUTO BOOT
QN48	√	√

GW1NSE-2C

Table 15 GW1NSE -2 C Configuration Modes

Configuration Modes	JTAG	AUTO BOOT
QN48	√	√
LQ144	√	√

GW1NSER-4C

Table 16 GW1NSER -4 C Configuration Modes

Configuration Modes	JTAG	AUTO BOOT
QN48G	√	√
QN48P	√	√

GW1NSR-4C

Table 17 GW1NSR -4 C Configuration Modes

Configuration Modes	JTAG	AUTO BOOT
MG64P	√	√

MIPI

GW1NS series of FPGA products support embedded MIPI interface modules. BANK0 of GW1NS-2 is MIPI input port and BANK2 is MIPI output

port. BANK0/BANK1 of GW1NS-4 is MIPI input and BANK2 supports MIPI output.

Note!

- For GW1NS-2C/2 devices of LX or UX version, V_{CC00} is set to 1.2V when BANK0 is used as MIPI input and V_{CC02} is set to 1.2V when BANK2 is used as MIPI output. And the MIPI speed of LX version is only 60% of that of UX version.
- When BANK0/BANK1 of GW1NS-4C/4 is used as MIPI input, V_{CC00}/V_{CC01} need to be set to 1.2V, and when BANK2 is used as MIPI output, V_{CC02} needs to be set to 1.2V; When V_{CCX} is set to 1.8 V, the speed of MIPI can only reach 60% of the speed of MIPI when V_{CCX} is set to 2.5V/3.3V.

ADC

GW1NS-2C/2 series of FPGA products integrate an eight-channel single-ended 12 bits SAR ADC. It is a medium-speed ADC with low-power, low-leakage current and high-speed.

Dynamic Performance

- Slew Rate: Max. 1MHz
- Dynamic range: >81 dB SFDR, >62 db SINAD
- Linear performance: INL<1 LSB, DNL<0.5 LSB, no missing codes

ADC Reference Voltage

- The reference voltage can be enabled or disabled by configuring parameters.
 $VREF_EN=1$, enabled;
 $VREF_EN=0$, disabled, and $Vref$ is provided by $Vccx$.
- When $Vref$ is enabled, there are two ways to provide $Vref$: internal and external.
The internal is provided by $Vccx$ and supports seven reference voltages by configuring $VREF_SEL$. The external is provided by $VREF$.

Note!

- It is recommended to add 10uF capacitance for ADC signal pin.
- It is recommended to use external reference voltage

USB

GW1NS-2C/2 is embedded with USB2.0 PHY with 480Mbps, USB1.1 1.5/12Mbps compatible, plug-and-play, hot-plug.

Note!

- The VBUS pin of FPGA chip needs to be connected to the VBUS of USB connector.
- The ID pin of FPGA chip needs to be connected to the ID of USB connector.
- The XIN and XOUT pins of FPGA chip need to be connected to the external 12Mhz crystal.
- The REXT pin of FPGA chip must be connected to the pull-down 12.7K with resistance of 1% accuracy.

Pinout

Before the design of the circuit, you should take the FPGA pinout into consideration, and a reasonable choice should be made for IO LOGIC, global clock resource, PLL and differential signals, etc.

Note!

During the configuration, all I/O (except TCK) of the device is weak pull-up, and I/O status after configuration is controlled by user programs and constraints.

Support and Feedback

Gowin Semiconductor provides customers with comprehensive technical support. If you have any questions, comments, or suggestions, please feel free to contact us directly by the following ways.

Website: www.gowinsemi.com

E-mail: support@gowinsemi.com

Revision History

Date	Version	Description
07/28/2020	1.0	Initial version published.

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